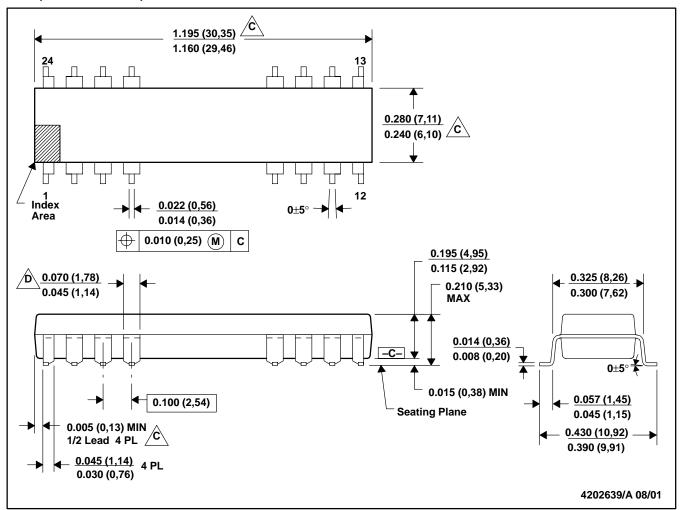
## **MECHANICAL DATA**

MPDS102 - AUGUST 2001

## DVL (R-PDSO-T16/24)

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- $\dot{c}$  Dimensions do not include mold flash or protrusions. A Mold flash or protrusions shall not exceed 0.010 (0,25).
- D. Maximum dimension does not include dambar
  - protrusions. Dambar protrusions shall not exceed 0.010 (0,25).
- E. Distance between leads including dambar protrusions to be 0.005 (0,13) minimum.
- F. A visual index feature must be located within the cross-hatched area.
- G. For automatic insertion, any raised irregularity on the top surface (step, mesa, etc.) shall be symmetrical about the lateral and longitudinal package centerlines.
- H. Controlling dimension in inches.



## **IMPORTANT NOTICE**

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgment, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

Customers are responsible for their applications using TI components.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, license, warranty or endorsement thereof.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations and notices. Representation or reproduction of this information with alteration voids all warranties provided for an associated TI product or service, is an unfair and deceptive business practice, and TI is not responsible nor liable for any such use.

Resale of TI's products or services with <u>statements different from or beyond the parameters</u> stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service, is an unfair and deceptive business practice, and TI is not responsible nor liable for any such use.

Also see: Standard Terms and Conditions of Sale for Semiconductor Products. www.ti.com/sc/docs/stdterms.htm

Mailing Address:

Texas Instruments Post Office Box 655303 Dallas, Texas 75265

Copyright © 2001, Texas Instruments Incorporated